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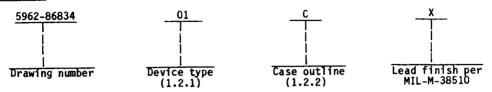
<u>DISTRIBUTION STATEMENT A.</u> Approved for public release; distribution is unlimited. **DESC FORM 193 MAY 86**



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1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

Circuit function Generic number Device type 54F243 Quad noninverting bus transceivers, 01 with three-state outputs

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	Case outline
C	D-1 (14-lead, 1/4" x 3/4"), dual-in-line package
D	F-2 (14-lead, 1/4" x 3/8"), flat package
2	C-2 (20-terminal, .350" x .350"), square chip carrier

1.3 Absolute maximum ratings.

Supply voltage range	-0.5 V dc to +7.0 V dc
Input voltage range	-1.5 V dc at -18 mA to +/.U V dc
Storage temperature	65°C to +150°C
Maximum power dissipation (Pn) per device 1/	495 mW
Lead temperature (soldering, 10 seconds) Thermal resistance, junction-to-case (θ _{JC}):	+300°C
Cases C and D	(See MIL-M-38510, appendix C)
Case 2	80°C/W <u>2</u> /
Junction temperature (T_J) $3/$	+175°C

1.4 Recommended operating conditions.

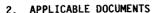
Supply voltage (V_{CC}) - - - - - - - - - - - - - - 4.5 V dc minimum to 5.5 V dc maximum Minimum high-level input voltage (V_{IH}) - - - - - - 2.0 V dc Maximum low-level input voltage (V_{IL}) - - - - - - - 0.8 V dc Normalized fanout (each output): 33 maximum 50 maximum -55°C to +125°C

Must withstand the added Pp due to short-circuit test (e.g., I_{OS}). When a thermal resistance for this case is specified in MIL-M-38510, appendix C, that value

shall supersede the value specified herein.

Maximum junction temperature shall not be exceeded except for allowable short duration burn-in screening conditions per method 5004 of MIL-STD-883.

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2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510

- Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
 - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and las specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.2 Truth table. The truth table shall be as specified on figure 2.
 - 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.
 - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

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	T		10	Lii	11-24		
Test	Symbol	Conditions -55°C < T _C < +125°C unless otherwise specified	Group A subgroups	Min	Max	Unit 	
High-level output voltage	v _{OH}	V _{CC} = 4.5 V; I _{OH} = -3 mA V _{IL} = 0.8 V; V _{IH} = 2.0 mA	1,2,3	2.4	 	V 	
	V _{OH1}	V _{CC} = 4.5 V; I _{OH} = -12 mA V _{IL} = 0.8 V; V _{IH} = 2.0 V	1,2,3	2.0	 	٧	
Low-level output voltage	V _{OL}	V _{CC} = 4.5 V; I _{OL} = 48 mA V _{IL} = 0.8 V; V _{IH} = 2.0 V	1,2,3		 .55 	٧	
Input clamp voltage	V _{IC}	I	1		-1.2	٧	
High-level input current	I _{IH1}	V _{CC} = 5.5 V; V _{IH} = 2.7 V	1,2,3		20	μА	
	I _{IH2}	 V _{CC} = 5.5 V; V _{IH} = 7.0 V enable inputs only	1,2,3		100	μА	
	IIH3	VCC = 5.5 V; VIH = 5.5 V	1,2,3		1.0	mA	

| VCC = 5.5 V EAB 1,2,3 |-0.3 |-1.0 | mΑ Low-level input current IILI | VIL = .5 V linput V_{CC} = 5.5 V |-.06 |-1.6 mΑ EBA 1,2,3 IIL2 input $V_{CC} = 5.5 \text{ V; } V_{OUT} = 0.0 \text{ V } 1/$ -100 -325 1,2,3 mΑ Short-circuit output current IOS 1,2,3 |-.03 |-1.6 mΑ | VCC = 5.5 V Low-level input, off-state IOZL low-output current $V_{IOZL} = 0.5 V$ μА |V_{CC} = 5.5 V 1,2,3 70 High-level input, off-state IIOZH |VIOZH = 2.7 V high-output current $V_{CC} = 5.5 \text{ V}$ $V_{IN} = 5.5 \text{ V}$ 80 mΑ 1,2,3 Supply current, high ICCH V_{CC} = 5.5 V V_{IN} = 0.0 V 92 mΑ 1,2,3 Supply current, low ICCL

See footnotes at end of table.

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	TAI	BLE	I.	Ele	ctrical	performance characteristics - C	ontinued.			
Test				Symbol	Conditions -55°C < T _C < +125°C unless otherwise specified	 Group A subgroups	Lim	Max	Unit	
Supply current, dis	sable				ICCZ	V _{CC} = 5.5 V V _{IN} = Open 	1,2,3		90	mA
Propagation delay time, Bn to An low-to-high level An to Bn Propagation delay time, Bn to An high-to-low level An to Bn		An		 V _{CC} = 5.0 V C _L = 50 pF ±10% <u>2</u> /	9,10,11		6.5	ns		
		Bn	tpLH2	R _L = 500Ω ±5% 	9,10,11	 	6.5	ns		
		An	tpHL1	 	9,10,11		8.5	ns		
		Bn	t _{PHL2}		9,10,11		8.5	ns		
Propagation delay E, E, C		, OE	t	o An	t _{PLZ1}	 	9,10,11	 	8.5	ns
to off-state	E, E	, OE	t	o Bn	t _{PLZ2}	 	9,10,11	 	8.5	ns
Propagation delay time, high level		, ŌE	t	o An	t _{PHZ1}	 	9,10,11	i 	7.5	ns
to off-state			o Bn	t _{PHZ2}	 	9,10,11		7.5	ns	
Propagation delay time, off-state	E, E	, 01	Εt	o An	tpZL1		9,10,11	 	10.5	ns
to low level	E, E	:, 01	Εt	o Bn	tpZL2		9,10,11		10.5	ns
Propagation delay time, off-state	E, E	্ৰ, তা	Εt	o An	tPZH1		9,10,11	 	8.0	ns
to high level E, E, C		Ξ, σ	Εt	o Bn	tpZH2		9,10,11	 	 8.0 	ns

 $[\]underline{1}/$ Not more than one output should be shorted at a time, and the duration of the short-circuit condition should not exceed one second.

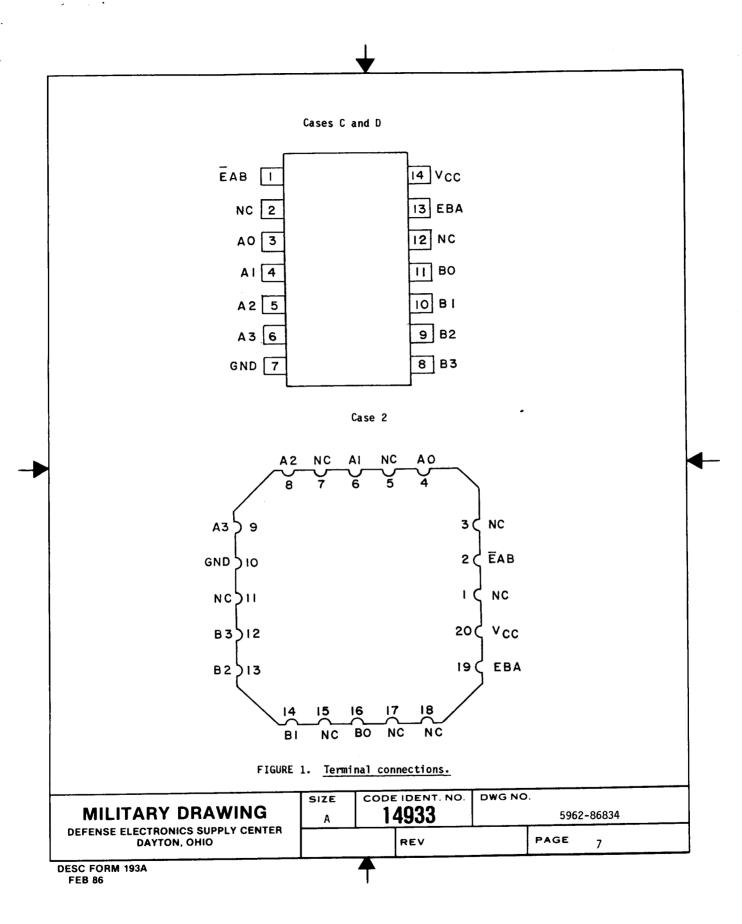
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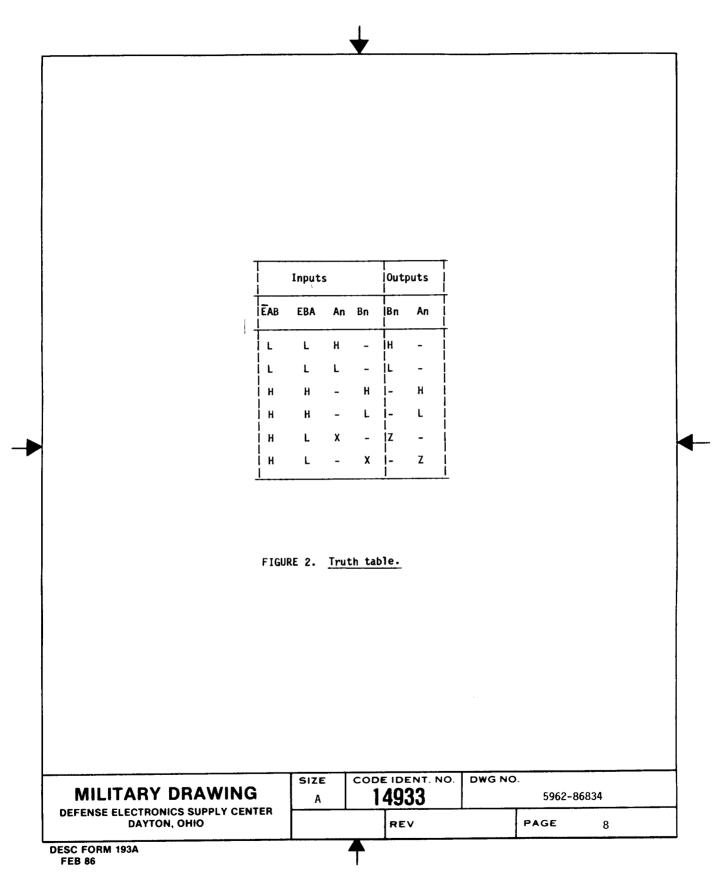
 $[\]frac{2}{C_L}$ Propagation delay time testing and maximum clock frequency testing may be performed using either C_L = 15 pF or C_L = 50 pF. However, the manufacturer must certify and guarantee that the microcircuits meet the switching test limits specified for a 50-pF load.



- 3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. OUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-SID-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test (method 1015 of MIL-STD-883).
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method $\overline{5005}$ of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 4, 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 7 tests shall verify the truth table.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

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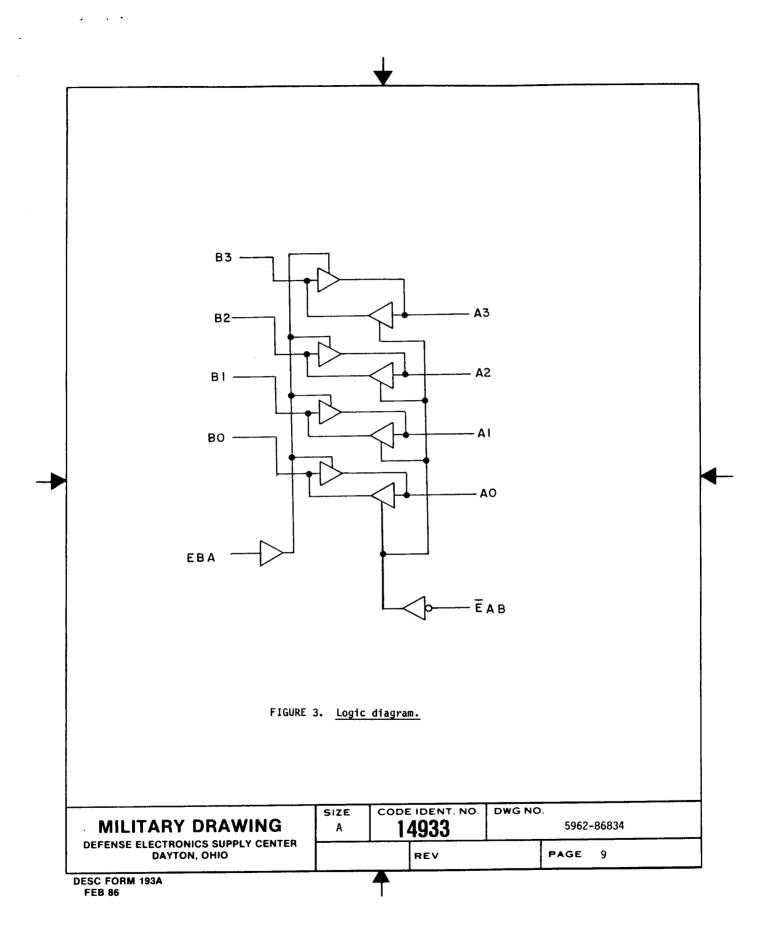


TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)	
 Interim electrical parameters (method 5004) 		
	1*, 2, 3, 9	
Group A test requirements (method 5005)	1, 2, 3, 7, 9, 10, 11**	
Groups C and D end-point lelectrical parameters ((method 5005)	1, 2, 3	

*PDA applies to subgroup 1.

5. PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
 - 6.2 Replaceability. Replaceability is determined as follows:
 - a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
 - b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/34802B--.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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^{**}Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

6.4 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1</u> /	Replacement military specification part number
8683401CX	07263 04713	54F243DMQB 54F243/BCAJC	M38510/34802BCX
8683401 DX	07263 04713	54F243FMQB 54F243/BDAJC	M38510/34802BDX
86834012X	07263 04713	54F243 LMQB 54F243 M/B2CJC	M38510/34802B2X

 $[\]frac{1}{}$ $\frac{\text{Caution.}}{\text{this number may not satisfy the performance requirements of this drawing.}}$

Vendor CAGE number	Vendor name <u>and address</u> Fairchild Semiconductor 333 Western Avenue South Portland, ME 04106	
07263		
04713	Motorola, Incorporated 7402 South Price Road Tempe, AZ 85283	

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